



CALL FOR PAPERS

August 17-20, 2023
Xi'an, Shaanxi, China



2023 IEEE 11th International Conference on Information, Communication and Networks

Track 15

The 2023 IEEE 11th International Conference on Information, Communication and Networks (ICICN) is set to take place in Xi'an, Shaanxi, China during August 17-20, 2023.



All submissions will be peer reviewed. Accepted, registered and presented papers will be published in the **ICICN 2023 IEEE conference Proceedings**, included in IEEE Xplore and indexed by **EI Compendex, SCOPUS**, etc.

Photonics and Optoelectronic Devices of 2D materials

Submission Deadline: June 10, 2023

Brief introduction

Atomically thin layered materials exhibit unique electrical and optoelectronic properties that hold promise in optoelectronic devices, including photodetectors, modulators, light sources, etc., which show promise as game-changer in emerging information technology. To push forward the application of this novel material family, mass production of wafer-scale 2D materials, optoelectronic device arrays for programmable sensor systems, and photonic devices integrated with Si photonics have been developed. Nevertheless, 2D material-based heterogeneous photonic and optoelectronics are still facing challenges in manufacturing readiness levels, which require further investigation including both fundamental exploration and application implementation.

Topics Interested topics include (but not limited to):

- 2D material synthesis
- 2D photonic device fabrication
- Photodetectors based on layered materials
- 2D neuromorphic devices/artificial synapses
- 2D metasurface
- Light-matter interaction in layered materials
- Photoresponse in 2D quantum materials
- 2D light emitting devices
- Ultrafast photonics in layered materials
- 2D smart materials for photonics

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